SPEAKER BIOGRAPHY – DALE LEE

Dale is a Senior Staff DFX Strategy Engineer with Plexus Corporation primarily involved with DFX analysis, root cause failure analysis and definition/correlation of design, process and tooling impacts on assembly processes and manufacturing yields.

Dale has been involved in surface mount design, package & process development and production for over thirty years in various technical and managerial positions. These activities have included research, development and implementation of advanced manufacturing technologies and interconnect techniques, design and development of Chip Scale Package (CSP) & Ball Grid Array (BGA) packages, PCB & PCBA support, DFM/DFX analysis of flex, rigid-flex & rigid PCB/PCBA’s including supply chain, process qualification and new process introduction for domestic and foreign low, medium and high volume production applications for consumer products, defense/aerospace and medical devices.

Dale has authored multiple technical articles and papers and is a frequent instructor/presenter globally on topics including PCB and SMT design, assembly, cleaning, and DFM/DFX. He is a past recipient of the Surface Mount Technology Association’s “Excellence in Leadership” award. He has been or is very involved with multiple industry associations (SMTA, IPC, INEMI), industry standards development, and symposium/conference technical development committees.